Customized Adhesive Solutions
25 B Street, Burlington, MA 01803
Phone: (978) 436-9600 Fax: (866) 788-7856
Email: info@nextgenadhesives.com

NGAC TC907-09 *Technical Bulletin*

Thermally Conductive and Electrically Insulating Adhesive

Description:
NGAC TC907-09 is a medium viscosity, electrically insulating and room temperature curing adhesive designed for staking and setting heat sensitive components in printed circuit board applications

Advantages and Applications:
NGAC TC907-09 provides strong and high impact bonds which improve heat transfer while maintaining electrical insulation. It bonds to a wide range of substrates including metals, glass and plastics. The NGAC TC907-09 has a low coefficient of thermal expansion and will provide excellent resistance to mismatched substrates and very low shrinkage. Additionally, the NGAC TC907-09 is highly resistant to chemicals.

NGAC TC907-09 features the following characteristics that enable ease of use.

Shelf life of each lot will be exactly 6 months from date of manufacture with storage at -40C Minimum.

Properties:	**Typical Value**
Color (Mixed)	Black
Mixed Viscosity	13,000 cps
Specific Gravity	1.70
Mix Ratio by Weight (R/H)	100/5.2
Hardness Shore D	90
Operating Temperature:	-70 to +125°C
Glass Transition Temperature	120°C
Thermal Conductivity, W/M/°K	0.56
CTE, cm/cm/°C	5.09E-05
Percent Solids	100%
Working Life***	30 minutes

Cure Schedule:

Temperature	25°C	65°C	95C
Time	72hr	2hr	1 hr

***Working life is subjective to application requirements.

For additional information or assistance, please call **978-436-9600**

All values reported above are typical values and are for reference use only. These values are not intended for use in developing specifications. Application testing under specific conditions should be performed to determine actual results and fitness for use.